

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20191014001 Datasheet for TPS3813K33-Q1, TPS3813I50-Q1 Information Only

Date: October 16, 2019 **To:** PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICETPS3813K33QDBVRQ1

CUSTOMER PART NUMBER

null

Technical details of this Product Change follow on the next page(s).

December		
Customer Contact: PCN Manager Change Type: □ Assembly Site □ Assembly Process □ Assembly Materials □ Assembly Materials □ Assembly Materials □ Part number change □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Wafer Bump Process □ Wafer Bump Process □ Wafer Fab Site □ Packing/Shipping/Labeling □ Test Site □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up		
Change Type: □ Assembly Site □ Design □ Wafer Bump Site □ Assembly Process □ Data Sheet □ Wafer Bump Material □ Assembly Materials □ Part number change □ Wafer Bump Process □ Mechanical Specification □ Test Site □ Wafer Fab Site □ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials □ Wafer Fab Process ■ Wafer Fab Process Notification Details Description of Change: □ Wafer Fab Process Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page • Updated text for device conditions on start-up. 7		
Assembly Site Design Wafer Bump Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. TEXAS INSTRUMENTS TPS3813K33-Q1, TPS3813I50-Q1 SPRS288G - MAY 2008 - REVISED OCTOBER 2019 Changes from Revision F (December 2016) to Revision G Page Updated text for device conditions on start-up. 7		
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Added information to further clarify shaded areas in the Upper and Lower Boundary Visualization		
The datasheet number will be changing.		
Device Family Change From: Change To:		
TPS3813K33-Q1, TPS3813I50-Q1		
These changes may be reviewed at the datasheet links provided.		
http://www.ti.com/product/TPS3813K33-Q1		
Reason for Change:		
To accurately reflect device characteristics.		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes		
to the actual device.		
to the actual device.		
to the actual device. Changes to product identification resulting from this PCN:		
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For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com

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